

Claims

1. A curable composition that forms a continuous phase and a dispersoid at normal temperatures, wherein
5 the continuous phase is a liquid at normal temperatures and comprises (a) a compound having two or more epoxy groups in a molecule, and the dispersoid comprises (b) a compound present as solid particles in a continuous phase at normal temperatures and
10 having two or more amino groups in a molecule.
2. The curable composition of claim 1, wherein the compound having two or more amino groups in a molecule is an aromatic amine compound having a benzoxazole structure.
15
3. The curable composition of claim 1 or 2, wherein the compound having two or more epoxy groups in a molecule is a liquid at normal temperatures.
- 20 4. The curable composition of any of claims 1 to 3, wherein the continuous phase contains an organic solvent having a boiling point of not higher than 200°C.
5. The curable composition of any of claims 1 to 4, wherein
25 the solid particles have a volume average particle size of 0.05 - 50 μm .